

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|--|------------------|
| 2 | 2 | ("5323060").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 17:11 |
| 3 | 15 | ("3851221" "4103318" "4361261" "4444349" "4567643" "4586642" "4730232" "4763188" "4982265" "5025306" "5040052" "5140404" "5172215" "5176311" "5177032").PN. | USPAT | 2002/11/07 17:11 |
| 4 | 74 | 5323060.URPN. | USPAT | 2002/11/07 17:13 |
| 5 | 74 | 5323060.URPN. | USPAT | 2002/11/07 17:15 |
| 1 | 135 | 257/685-686.ccls. and (conductive adj adhesive) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 18:03 |
| 6 | 2442 | (257/\$.ccls. 438/\$.ccls.) and (conductive adj adhesive) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 17:28 |
| 7 | 691 | (257/\$.ccls. 438/\$.ccls.) and (conductive adj adhesive) and (flip adj (chip die IC)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 17:46 |
| 8 | 4 | ((("5399898") or ("5323060")).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 17:44 |
| 9 | 604 | (257/\$.ccls. 438/\$.ccls.) and (conductive adj adhesive) and (flip adj (chip die IC)) and wir\$4 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 17:54 |
| 10 | 115 | (257/\$.ccls. 438/\$.ccls.) and (electrical\$4 adj conductive adj adhesive) and (flip adj (chip die IC)) and wir\$4 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 17:56 |
| 11 | 20 | 257/685-686.ccls. and ((electrical\$4 adj conductive adj adhesive) ECA) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 18:04 |
| 12 | 96 | 257/685-686,723-724,777-778.ccls. and ((electrical\$4 adj conductive adj adhesive) ECA) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 2002/11/07 18:20 |
| 13 | 17 | 438/107,109-110.ccls. and ((electrical\$4 adj conductive adj adhesive) ECA) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/11/07 18:21 |